

International Conference on

ADVANCES IN MATERIALS PROCESSING AND CHARACTERIZATION (ICAMPC-2019)



September 10-11, 2019



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Organized by
DEPARTMENTS OF MECHATRONICS, MECHANICAL, AERONAUTICAL & AUTOMOBILE ENGINEERING

ABOUT THE CONFERENCE

ICAMPC 2019 organizing committee cordially welcomes everyone to the International Conference on Advances in Materials Processing and Characterization which will be held during September 10 & 11, 2019 in Sathyamangalam, India. This comprises keynote sessions, oral presentations and poster competitions.

TOPICS OF INTEREST (Not limited to...)

- Additive Manufacturing
- Powder Metallurgy
- Composites
- Surface Engineering
- Green Manufacturing
- Metal Joining
- Materials Testing
- Nanomaterials
- Numerical Modelling and Simulation
- Energy Materials
- Smart Materials

REGISTRATION FEES

Research Scholar (Full Time)	Rs. 6000 / \$ 100
Academician	Rs. 6000 / \$ 100
Industry Personnel	Rs. 7000 / \$ 120

IMPORTANT DATES

Full Paper Submission	July 1, 2019
Paper Acceptance	July 29, 2019
Registration	August 10, 2019

MODE OF PAYMENT (ONLINE/CASH/DD*)

Account Name	BIT-Centre for Advance Studies
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PUBLICATIONS

All the selected conference papers will be published in AIP or IOP Publishing.



IOP Publishing